



### Materials Declaration

<b>Package</b>	CSP_BGA 2 layer
<b>Body Size</b>	12x12mm
<b>LeadCount</b>	74
<b>Option</b>	SnAgCu
<b>Ball Size</b>	0.6 mm

#### Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO <sub>2</sub> Filler	87.0	1.50 E-01	360552
Epoxy resin	13.0	2.24 E-02	53842
Sb <sub>2</sub> O <sub>3</sub>	0.8	1.40 E-02	33652

#### Laminate

Item	% of Laminate	Weight (g)	PPM
Laminate	63.2	6.80 E-02	163450
Cu	15.2	1.66 E-02	39901
Solder mask	13.2	1.44 E-02	34613
Nickel	4.6	5.50 E-03	13220
Brominated Compound	3.0	3.20 E-03	7692
Gold	0.8	9.00 E-04	2163

#### Solder Ball

Item	% of Plating	Weight (g)	PPM
Sn	96.5	7.52 E-02	180757
Ag	3.0	2.30 E-03	5528
Cu	0.50	4.00 E-04	961

#### Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.94 E-03	4673

#### Chip

Item	% of Chip	Weight (g)	PPM
Si	100.0	3.60 E-02	86496

#### Die Attach

Item	% of Die Attach	Weight (g)	PPM
Filler	75.0	3.90 E-03	9374
Resin	25.0	1.30 E-03	3125

Weight (g)	PPM
4.16 E-01	1000000

AMK-BC-E

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

7/11/2006





## Materials Declaration

<b>Package</b>	CSP BGA 2 layer
<b>Body Size</b>	12 X 12
<b>Ball Count</b>	74
<b>Option</b>	SnPb
<b>Ball Size</b>	0.6 mm

### Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	89.0	1.54 E-01	366570
Resin	11.0	1.91 E-02	45376
Brominated Compound	0.9	1.60 E-03	3801
Sb2O3	0.5	9.00 E-04	2138

### Molding Compound

Item	PPM	Method
Pb	1.50	ICP-MS
Cd	< 0.1	ICP-MS
Hg	< 0.1	ICP-MS
Cr+6**	12.9*	ICP-MS

\*\* Cr+6 Included in the \*total Cr content

### Laminate

Item	% of Laminate	Weight (g)	PPM
BT-Epoxy	63.2	6.88 E-02	163448
Copper	15.2	1.66 E-02	39437
Solder Mask	13.2	1.44 E-02	34210
Nickel	4.6	5.50 E-03	13066
Brominated Compound	2.9	3.20 E-03	7602
Gold	0.8	9.00 E-04	2138

### Die Attach Paste

Item	PPM	Method
Pb	5.00	US EPA Method 3052. ICP-OES
Cd	Not Detected	US EPA Method 3052. ICP-OES
Hg	Not Detected	US EPA Method 3052. ICP-OES
Cr+6	Not Detected	US EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	Analysis was performed by GC/MS
PBDE	Not Detected	Analysis was performed by GC/MS

### Solder Ball

Item	% of Solder Ball	Weight (g)	PPM
Sn	63.0	5.83 E-02	138503
Pb	37.0	3.43 E-02	81486

### Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.9	1.94 E-03	4619

### Chip

Item	% of Chip	Weight (g)	PPM
Si	100.0	3.60 E-02	85489

### Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	77.0	3.90 E-03	9265
Resin	23.0	1.20 E-03	2851

### Package Totals

Weight (g)	PPM
4.21E-01	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge  
 ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to  
 any inaccuracy of such information

